

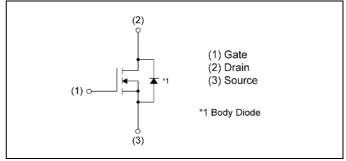
V <sub>DSS</sub>	600V
R <sub>DS(on)</sub> (Max.)	0.165Ω
I <sub>D</sub>	±24A
P <sub>D</sub>	74W

# ● Outline TO-3PF

## Features

- 1) Low on-resistance.
- 2) Ultra fast switching speed.
- 3) Parallel use is easy.
- 4) Pb-free lead plating; RoHS compliant

# •Inner circuit



Packaging specifications

jiiig opcomoduciio	
Packing	Tube
Reel size (mm)	-
Tape width (mm)	-
Quantity (pcs)	300
Taping code	C17
Marking	R6024KNZ
	Reel size (mm) Tape width (mm) Quantity (pcs) Taping code

# Application

Switching

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	600	V
Continuous drain current (T <sub>c</sub> = 25	5°C)	I <sub>D</sub> *1	±24	Α
Pulsed drain current	l <sub>DP</sub> *2	±72	Α	
Cata Carman valtage	static		±20	V
Gate - Source voltage AC(f>1Hz)		$V_{GSS}$	±30	V
Avalanche current, single pulse	·	I <sub>AS</sub>	4.1	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	497	mJ
Power dissipation (T <sub>c</sub> = 25°C)		P <sub>D</sub>	74	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage te	emperature range	T <sub>stg</sub>	-55 to +150	°C

# ●Thermal resistance

Davamatav	Cymah al	Values			l lm:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	1.7	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	40	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cumb al	Symbol Conditions		Values			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	600	-	-	V	
		V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V					
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ	
drain canoni		$T_j = 125^{\circ}C$	-	-	1000		
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3	-	5	V	
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 11.3A					
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$T_j = 25^{\circ}C$	-	0.150	0.165	Ω	
		$T_j = 125^{\circ}C$	-	0.32	-		
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	1.9	-	Ω	

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Cy reads ad	Symbol Conditions		Values			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Forward Transfer Admittance	$ Y_{fs} ^{*5}$ $V_{DS} = 10V, I_D = 12A$		6.5	13.0	-	S	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2000	-	,	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	1500	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	60	1		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	30	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 12A	-	50	-	20	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 27.4\Omega$	-	60	-	ns	
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	12	1		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	C: made al	Conditions	Values			l limit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ 300V	-	45	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 24A	-	13	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	20	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 24A	-	6.8	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 70mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T $_{j}$ =25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Pulsed

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Cumbal	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Urill	
Continuous forward current	I <sub>S</sub> *1	T - 25°C	-	-	24	А	
Pulse forward current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	72	А	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 24A	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5		-	510	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 24A   di/dt = 100A/µs	-	9.0	-	μC	
Peak reverse recovery current	I <sub>rrm</sub> *5	100/ Vµ0	-	32.5	-	Α	

Typical transient thermal characteristics

Symbol	Value	Unit
R <sub>th1</sub>	0.108	
R <sub>th2</sub>	0.549	K/W
R <sub>th3</sub>	1.22	

Symbol	Value	Unit
C <sub>th1</sub>	0.00523	
C <sub>th2</sub>	0.045	Ws/K
C <sub>th3</sub>	1.07	

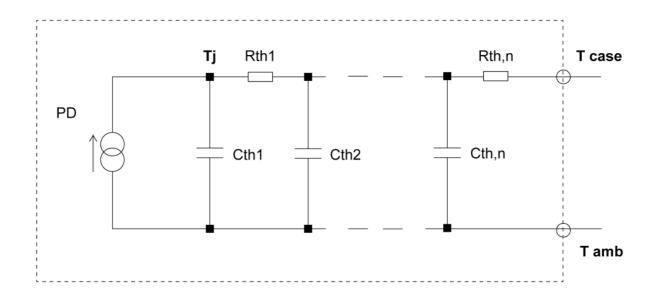


Fig.1 Power Dissipation Derating Curve

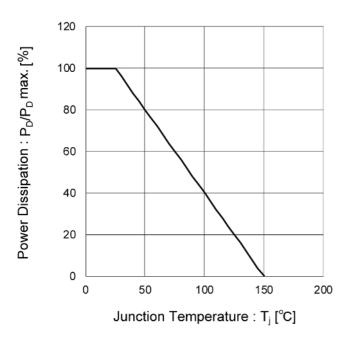


Fig.2 Maximum Safe Operating Area

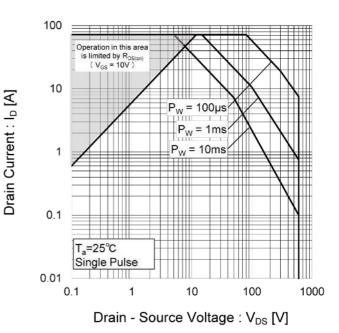


Fig.3 Avalanche Energy Derating Curve vs. Junction Temperature

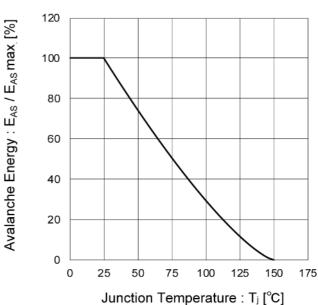


Fig.4 Typical Output Characteristics(I)

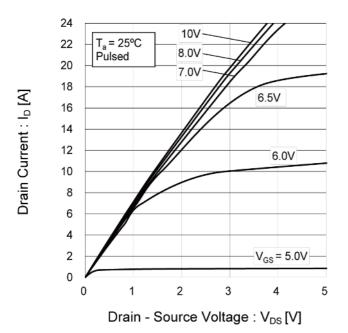
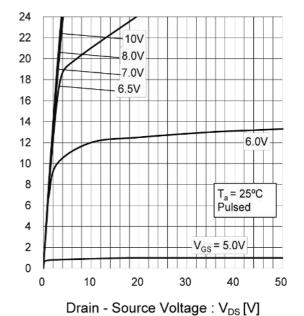


Fig.5 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

ROHM

Fig.6 Breakdown Voltage vs.

Junction Temperature

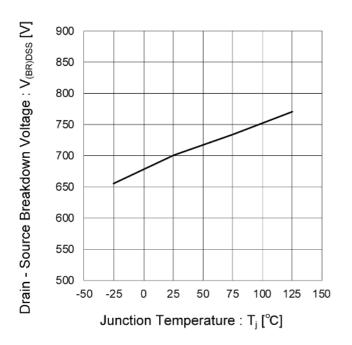


Fig.7 Typical Transfer Characteristics

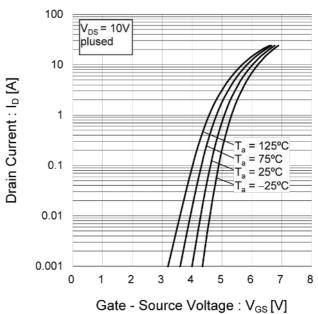


Fig.8 Gate Threshold Voltage vs.
Junction Temperature

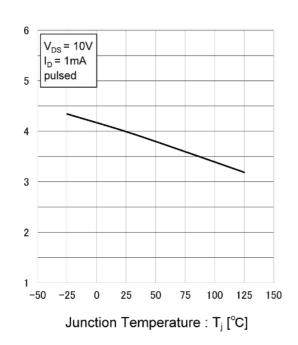
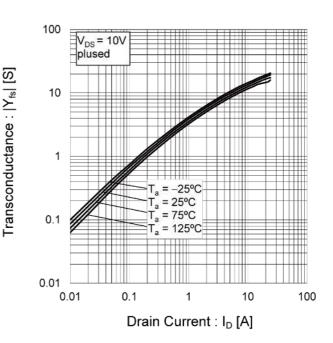


Fig.9 Forward Transfer Admittance vs.
Drain Current



Gate Threshold Voltage: V<sub>GS(th)</sub> [V]

Fig.10 Static Drain - Source On - State Resistance vs. Gate Source Voltage

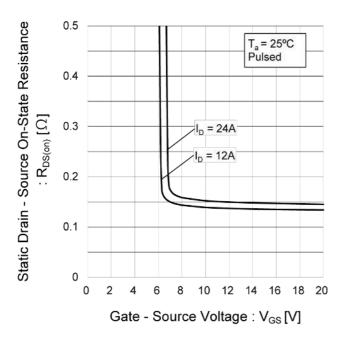


Fig.11 Static Drain - Source On - State Resistance vs. Junction Temperature

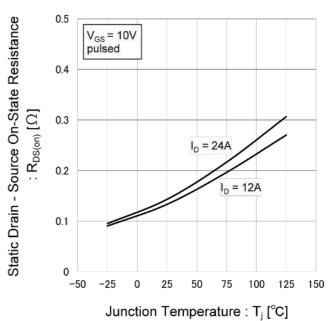


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current(I)

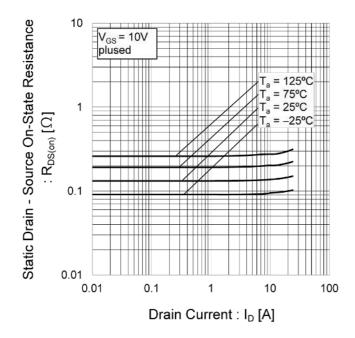
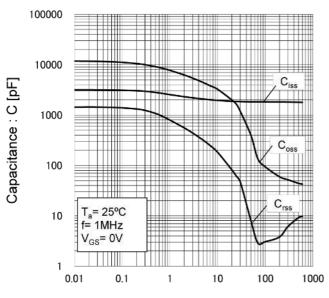


Fig.13 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.14 Switching Characteristics

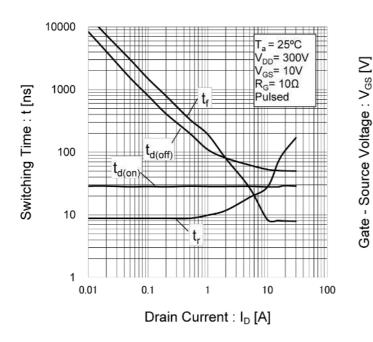


Fig.15 Dynamic Input Characteristics

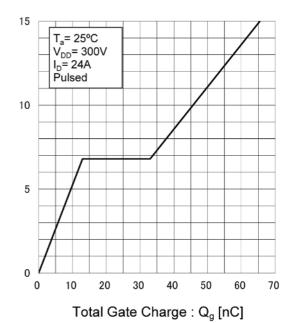
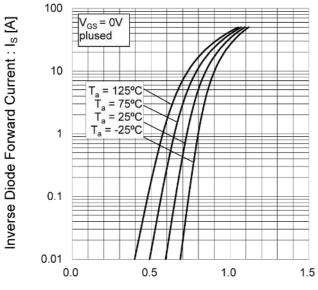
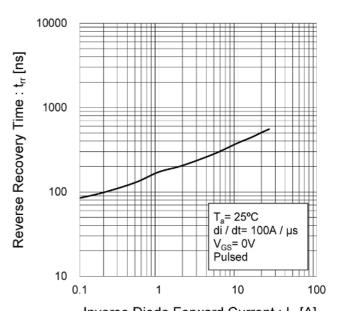


Fig.16 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Fig.17 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I<sub>S</sub> [A]

#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

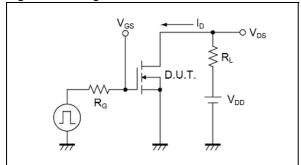


Fig.2-1 Gate Charge Measurement Circuit

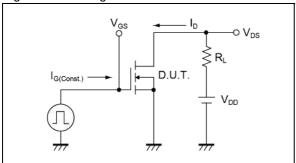


Fig.3-1 Avalanche Measurement Circuit

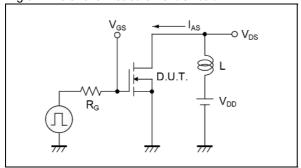


Fig.4-1 dv/dt Measurement Circuit

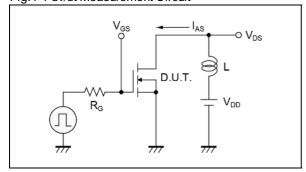


Fig.5-1 di/dt Measurement Circuit

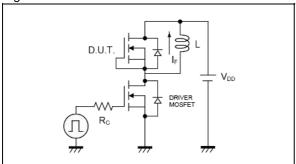


Fig.1-2 Switching Waveforms

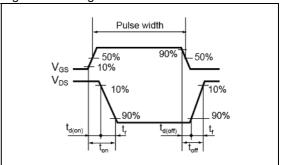


Fig.2-2 Gate Charge Waveform

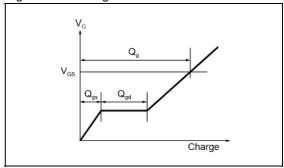


Fig.3-2 Avalanche Waveform

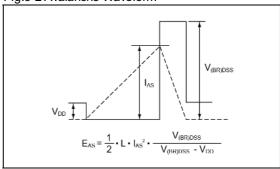


Fig.4-2 dv/dt Waveform

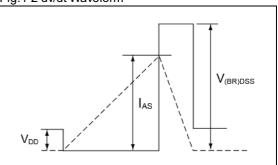
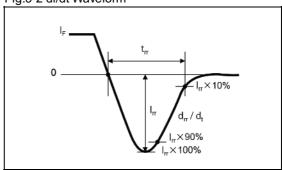
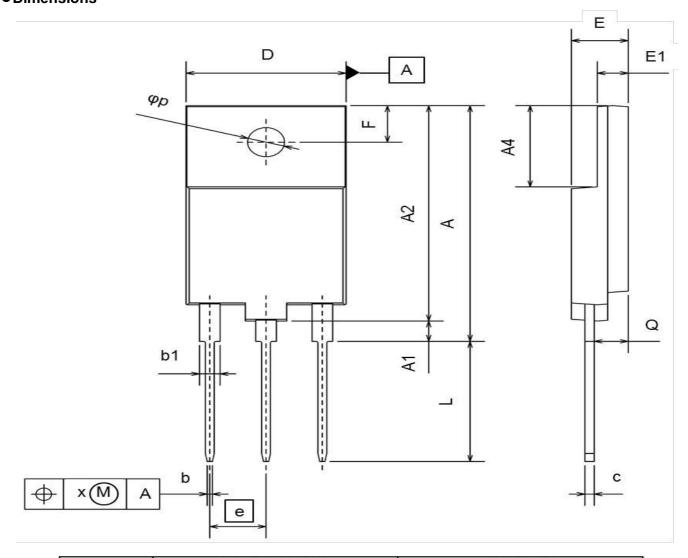


Fig.5-2 di/dt Waveform



# Dimensions



DIM	MILIMETERS		INCH	HES
DIIVI	MIN	MAX	MIN	MAX
Α	28.60	29.40	1.126	1.157
A1	2.30	2.70	0.091	0.106
A2	26.30	26.70	1.035	1.051
A4	9.80	10.20	0.386	0.402
b	0.66	0.95	0.026	0.037
b1	1.80	2.20	0.071	0.087
С	0.80	1.00	0.031	0.039
D	15.30	15.70	0.602	0.618
E	5.30	5.70	0.209	0.224
E1	2.80	3.20	0.110	0.126
е	5.	45	0.2	15
F	4.35	4.65	0.171	0.183
L	14.60	15.00	0.575	0.591
φp	3.40	3.80	0.134	0.150
Q	3.10	3.50	0.122	0.138
Х	-	0.50	Œ	0.020

Dimension in mm / inches

# **Notice**

#### **Precaution on using ROHM Products**

Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

## **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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